photosensitive chip mounted to the substrate, a plurality of wires for electrically connecting the photosensitive chip to the substrate, a frame layer mounted to the substrate to surround the photosensitive chip. And a transparent layer is fixed and encapsulated by the frame layer such that the photosensitive chip may receive optical signals passing through the transparent layer.

According to above- mentioned structure of the present invention has the following advantage.

1. Since the periphery of the transparent layer 48 is inserted into the frame layer 46, the periphery does not have to be chamfered. Thus, the manufacturing processes may be simplified, and the manufacturing cost may be reduced.

2. Since the periphery of the transparent layer 48 is free from being damaged, broken, or contaminated, the product quality may be effectively enhanced.

3. Since the frame layer 46 is mounted to the substrate 40 after the wires are bonded from the photosensitive chip 42 to the substrate 40, the wire bonding process may be simplified.

Therefore, the present invention does not disclose frame layer forming thread to screw to the external thread of the lens barrel.

Thus, the Hsin does not disclose a similar structure to that of this application, and does not motivate the Applicant to finish this application. Reconsideration of the Claims 1 is politely requested.

In light of the above remarks, Applicant now asserts that all of the grounds for rejection have been traversed or overcome by the detailed arguments, and that all of the present claims are in condition for immediate allowance. Applicant therefore requests reconsideration of the rejections, and solicits allowance of the

present claims at an early date.

Thank you for your consideration.

Respectfully submitted,

Date: 2/16 2005 Jichen WU

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